EAST Search History

| Ref # | Hits | Search Query | DBs | Default Operator | Plurals | Time Stamp |
|----------|------|---|---|---------------------|---------|------------------|
| L1 | 1500 | 372/34.ccls. | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/06/05 13:16 |
| L2 | 1102 | 372/36.ccls. | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/06/05 13:16 |
| L3 | 2 | 1 and (heat\$sink\$3 same (semiconductor adj laser) same (bonding brazing)) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/06/05 13:18 |
| L4 | 6 | 2 and (heat\$sink\$3 same (semiconductor adj laser) same (bonding brazing)) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/06/05 13:18 |
| L5 | 38 | (heat\$sink\$3 same (semiconductor adj laser) same (bonding brazing)) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/06/05 13:18 |
| L6 | 5 | (heat\$sink\$3 same (semiconductor adj laser) same (bonding brazing)).clm. | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/06/05 13:18 |



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